**TRANSMITTAL OF FORMAL DRAWINGS**Docket No.
SLA0709

Application Of: Tingkai Li, Wei Pan, Robert A. Barrowcliff, David R. Evans and Sheng Teng Hsu

Serial No.	Filing Date	Batch No.	Examiner	Art Unit
10/621,863	07/16/2003		Hsien Ming Lee	2823

Invention: MOCVD of TiO₂ Thin Film for Use as FeRAM H₂ Passivation Layer

Address to:

Assistant Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith are:

4 sheets of formal drawing(s) for this application.

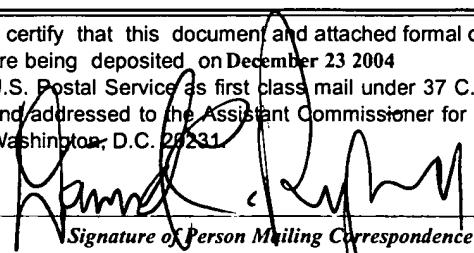
Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c)
on the reverse side of the drawing.

Signature

David C. Ripma, Patent Counsel
Registration No. 27,672
Sharp Laboratories of America, Inc.
5750 NW Pacific Rim Boulevard
Camas, WA 98607
Phone: 360-834-8754
Facsimile: 360-817-8505

Dated: December 23, 2004

I certify that this document and attached formal drawings
are being deposited on December 23 2004 with the
U.S. Postal Service as first class mail under 37 C.F.R. 1.8
and addressed to the Assistant Commissioner for Patents,
Washington, D.C. 20231



Signature of Person Mailing Correspondence

David C. Ripma, Reg. #27,672

Typed or Printed Name of Person Mailing Correspondence